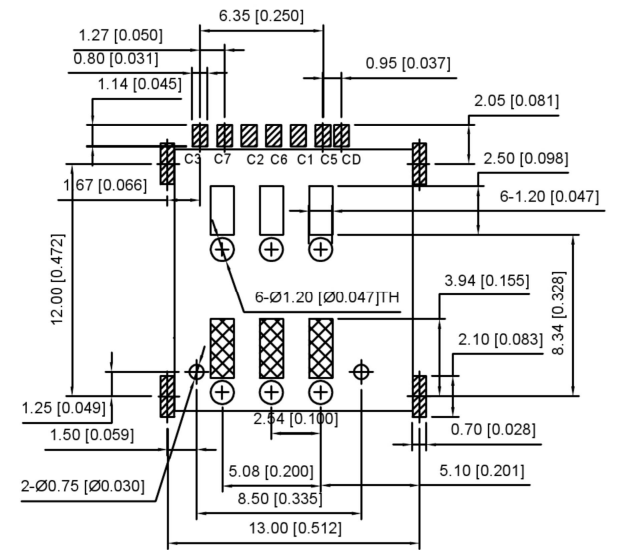
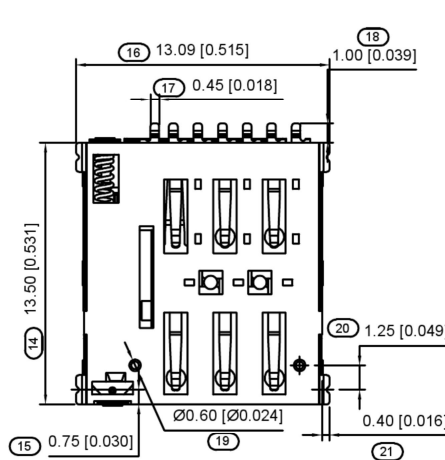


SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

NOTES:

- MATERIAL:**
HOUSING: HI-TEMP. PLASIC UL 94V-0
TERMINAL: COPPER ALLOY
SHELL: SUS
- PLATING:**
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: Au GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:**
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50m Ω MAX
3.4 Insulation Resistance: 1000M Ω MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260 \pm 0/-5 $^{\circ}$ C, 30 \pm 10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40 $^{\circ}$ C ~ +85 $^{\circ}$ C;
Humidity 80% R.H MAX

PAD
 KEEP OUT AREA

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

REVISIONS	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
				ANGULAR $\pm 5^{\circ}$
				$L \leq 4$ ± 0.2
				$4 < L \leq 16$ ± 0.3
				$16 < L \leq 63$ ± 0.4
				$L > 63$ ± 0.5



DSND	SCALE: N/A	MODEL TYPE:		
DWN	VIEW:	SIM CARD CONN		
CHKD	UNIT: mm/in	PART NO.: XKNANO-113		
APPD	SIZE: A4	DWG NO.:		
		WEIGHT	SHEET	REVISION
			1/1	A0